

## **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>RM</sub>	60	V
Average Rectified Output Current	lo	2	Α
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I <sub>FSM</sub>	35	Α

## **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Case (Note 6) Typical Thermal Resistance Junction to Ambient (Note 6)	R <sub>0JC</sub> R <sub>0JA</sub>	40 100	°C/W
Operating and Storage Temperature Range	$T_J$ , $T_{STG}$	-55 to +175	°C

# **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

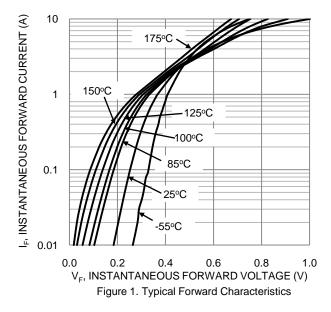
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 8)	$V_{(BR)R}$	60	_		V	$I_R = 1.0 \text{mA}$
		_	0.37	0.46		$I_F = 1A, T_J = +25^{\circ}C$
Forward Voltage Drop	VF	_	0.44	0.51	V	$I_F = 2A, T_J = +25^{\circ}C$
		_	0.42			I <sub>F</sub> = 2A, T <sub>J</sub> = +125°C
		_	20	_	μA	$V_R = 10V, T_J = +25$ °C
Leakage Current (Note 8)	$I_R$	_	50	150	μA	$V_R = 60V, T_J = +25^{\circ}C$
		_	6.5	-	mA	$V_R = 60V, T_J = +125$ °C
Total Capacitance	Ст	_	75	_	pF	V <sub>R</sub> = 10V, f = 1MHz

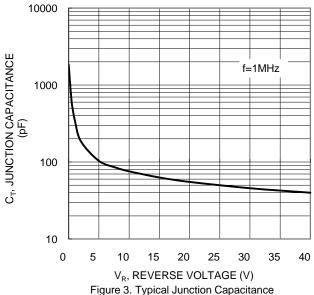
Notes:

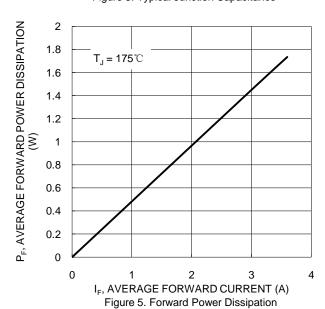
- 6. Device mounted on FR-4 substrate, 0.4"\*0.5", 2oz, single-sided, PC boards with 0.2"\*0.25" copper pad. 7. Device mounted on FR-4 substrate, 1.0"\*1.0", 2oz, single-sided, PC boards with 0.2"\*0.25" copper pad. 8. Short duration pulse test used to minimize self-heating effect.

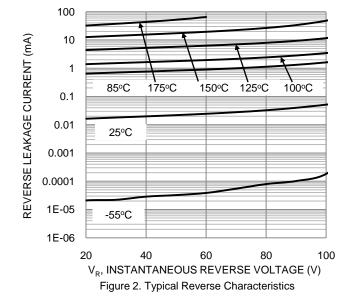












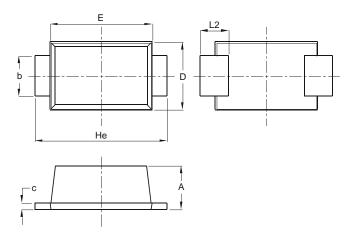
Io AVERAGE RECTIFIER OUTPUT CURRENT (A) 2.50 2.00 Note 7 1.50 1.00 0.50 0.00 175 25 75 100 125 150  $T_A$ , AMBIENT TEMPERATURE (°C) Figure 4. DC Forward Current Derating



# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

## SOD123F

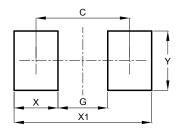


SOD123F				
Dim	Min	Max	Тур	
Α	0.81	1.15	ı	
b	0.80	1.35	-	
С	0.05	0.30	-	
D	1.70	1.90	1.80	
Е	2.60	2.80	2.70	
He	3.30	3.70	3.50	
L2	0.35	0.85	-	
All Dimensions in mm				

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### SOD123F



Dimensions	Value (in mm)
С	2.86
G	1.52
Х	1.34
X1	4.20
Y	1.80



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